

GLOBAL SEMICONDUCTOR & ELECTRONICS FORUM

CONNECTING TECHNOLOGY LEADERS

San Diego, California
26-27 October 2023

GSEF 2023

DAY ONE – 26th October 2023

08:00	Event registration and collection of meeting schedules
08:55	Welcome address and Chair's opening remarks.
09:00	<p>OPENING ADDRESS: Sustained U.S. chip innovation leadership</p> <ul style="list-style-type: none"> • Importance of government-industry collaboration • Targeted funding for semiconductor R&D ecosystem • Investing in highly skilled R&D workforce
09:25	<p>PRESENTATION - AMD's Vision for Adaptive Computing - Salil Rajee, SVP & GM of Adaptive and Embedded Computing Group, AMD</p> <p>Technology is the foundation of our society. It delivers interpersonal connections, security, productivity, entertainment, and many more unique and personal experiences. Our electronics-driven world requires more than speeds and feeds. It requires computing that can adapt to people's expectations. Today's systems-on-chips, with their arrays of processors, programmable logic, AI engines, and high-speed interfaces, are ideal for mobile apps, wearables, and embedded systems of any kind. With increasingly demanding high-speed/low-latency applications at the edge and in the cloud, adaptive computing is an essential part of the technology landscape. While the complexity of today's adaptive devices has increased dramatically, adaptive computing technology has become more accessible for both hardware and software developers, who may now access adaptive devices within familiar developer workflows and environments with no hardware expertise required. With the advancement of high-level languages and AI frameworks, they can target adaptive devices to accelerate specific applications and shorten time to productivity and market. Adaptive computing delivers performance where other options only impose constraints. In this session, we'll cover how the evolution of the FPGA and the rise of AI have ushered the era of adaptive computing and why AMD is primed to lead the industry forward.</p>
09:55	PRESENTATION – Dr. Raman Achutharaman, Group VP of the Joint Operations Leadership Team, Applied Materials
10:30	Business Meeting 1
10:55	Business Meeting 2
11:15	<p>PRESENTATION: Innovations beyond the mainstream CMOS for a sustainable digital society - Antti Vasara, CEO, VTT Technical Research Centre of Finland</p> <ul style="list-style-type: none"> • VTT turns science into practical innovations through applied research. • To reach carbon neutrality, we develop new material and device architectures with focus in 6G and edge computing.

11:45	<p>PRESENTATION: Supply Chain: The frontline for managing risk and enabling growth - Jackie Sturm, CVP, Global Supply Chain Operations, Intel</p> <ul style="list-style-type: none"> ○ The supply chain challenges of the past few years have highlighted the growing scope and scale of risks that confront businesses. ○ Additionally, corporate expectations, whether from shareholders, employees, or regulators, requires a complex balancing act to navigate. ○ The talk will focus in on emerging opportunities and challenges as companies attempt to deliver across ESG/CSR
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12:15	LUNCH AND NETWORKING
13:15	Business Meeting 3
13:40	Business Meeting 4
14:00	<p>PRESENTATION: Ushering in the Hyperconnected Era - James Livingston, Director, TATA Communications</p> <ul style="list-style-type: none"> ● Connectivity - the transition from convenience to dependency ● Being connected isn't enough, it's time for hyperconnectivity. ● How connectivity platforms are solving real-world problems and creating new business opportunities
14:25	<p>PRESENTATION: How AI Is Reshaping Semiconductor industry: Exploring the next wave of AI technologies and applications</p>
14:55	Business Meeting 5
15:15	Business Meeting 6
15:40	<p>PRESENTATION: Dr. Sandeep Kumar, SVP of Worldwide Operations, Silicon Labs</p>
16:05	Business Meeting 7

16:30	Business Meeting 8
16:55	PRESENTATION: SiC: Enabling E-Mobility and FAST Charging - Asif Jakwani, SVP and GM of Advance Power Division, onsemi
17:30	Closing remarks followed by drinks reception
18:00	Drinks & Dinner
Day 2	
08:30	Event registration and collection of meeting schedules
08:55	Chair's opening remarks
09:00	PRESENTATION: Michigan Economic Development Corporation
09:30	Fireside chat: Heterogeneous Compute for high performing specialised processing: driving new multichip innovation and standardisation. Navid Shahriari, SVP and Co-General Manager, Design Engineering Group, Intel
10:05	PRESENTATION: Jon Herlocker, CEO, Tignis
10:35	PRESENTATION: Exploring the Blueprints for Software Defined Vehicles - Shelly Van Dyke, VP Automotive Processing Strategy, NXP Semiconductors Carmakers are moving to deliver on the promise of software defined vehicles. While the architectures and trajectories of these efforts vary, they are united in their ambition to reinvent cars, providing updateable features, enhanced functionality, and new customer experiences – changes that are rapidly defining a new era in automotive. Join NXP's Shelly Van Dyke, Vice President, Automotive Processing Strategy as she explores the challenges and misconceptions of emerging SDVs as well as the architectures, and hardware and software solutions that will power their success.
11:10	Business Meeting 9
11:35	Business Meeting 10

12:00	<p>PANEL DISCUSSION: Future of Advanced Packaging Technology Development for Chiplets (Focus on new materials and architecture, designs, manufacturing processes and new methodologies to bring diverse components together)</p> <p>Dirk Schade Global Business Development, XYZTEC Mark Kuemerle is VP of Technology and CTO for Custom Solutions, Marvell Koushik Banerjee is VP Technology and Manufacturing Group, Intel</p>
12:40	LUNCH AND NETWORKING
13:40	<p>PRESENTATION: Accelerating Cloud Compute and AI with Cloud-Optimized Silicon – Mark Kuemerle, VP of Technology and CTO for Custom Solutions ,Marvell</p> <ul style="list-style-type: none"> • Generative AI is having a massive impact on data center infrastructure, requiring a re-thinking of compute architecture along with a whole new level of cloud silicon optimization. • This talk will start with a historical perspective on cloud data center compute and how the evolution from general purpose to accelerators and, more recently, to custom and cloud-optimized silicon have led to the hyperscale growth the largest cloud service providers enjoy today. • We will explore how the expansion from basic enterprise computing applications to data intensive networking and security use cases laid the foundation for today's accelerated compute technologies, most notably, GPUs and DPUs and the benefits of this transition. • We will also draw lessons from these experiences that are relevant to emerging cloud native 5G RAN deployments and lay out the silicon requirements needed for vRAN systems to match the performance and energy efficiency of established 5G radio networks.
14:10	<p>PRESENTATION: Advanced Packaging Innovations – Koushik Banerjee, VP Technology Development Group at Intel Corporation and co-leads Assembly and Test Technology Integration.</p> <p>Advanced Packaging is central to semiconductor leadership in a world where semiconductors are everywhere. Heterogeneous integration and modular design using advanced packaging technologies is enabling high-performance products. System Technology Co-optimization is a key enabler for the future. This presentation will cover trends and future directions in advanced packaging.</p>
14:40	PRESENTATION: Kedar Soman, CTO & Co-founder ebikeGo
14.55	<p>PRESENTATION: Building a Secure 5G Architecture</p> <ul style="list-style-type: none"> • How to ensure security for new use cases in an evolving technology world • 5G and national security implications - How will 5G improve intelligence, surveillance, and reconnaissance systems and processing. • Analysing how 5G will impact disruptive technologies and digital experience.

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